STATSChipPAC™

Shaping Solutions for Tomorrow

About STATS ChipPAC

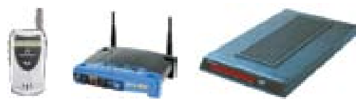
STATS ChipPAC Ltd. is a leading service provider of semiconductor packaging design, assembly, test and distribution solutions. A trusted partner and supplier to leading semiconductor companies worldwide, STATS ChipPAC's value proposition is total solutions comprising fully integrated, multi-site, end-to-end assembly and test solutions that bring products to market and volume faster.

Our customers include some of the largest wafer foundries, integrated device manufacturer's (IDMs), as well as fabless companies worldwide.

STATS ChipPAC is a leader in mixed-signal testing and advanced packaging technology for semiconductors used in diverse end market applications including communications, digital consumer and computing.

- One of the broadest portfolios of assembly and test solutions in the industry
- Second largest test house globally
- Full turnkey solutions for 3D and wireless applications

Communications



- Strong communications heritage
- Leader in mixed-signal test
- Comprehensive portfolio of RF/mixed-signal test using the industry's most advanced platforms

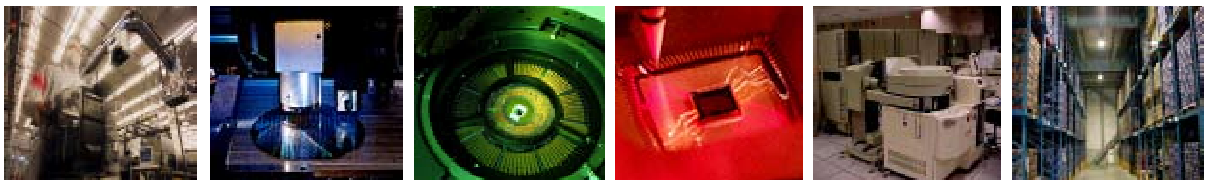
Consumer

- Leadership in advanced stacked die packaging for small form factor consumer applications
- Chip scale packages, stacked die, stacked package, flip chip, wafer level and System-in-Package

Computing

- Long history of providing advanced solutions to major computing players
- Use of the latest substrate and assembly technology improves functionality, efficient use of motherboard real estate and reduces cost

Integrated Turnkey Solutions



Wafer process / RDL | Bump | Probe | Assembly | Final Test | Drop Ship

As more functionality is incorporated into a single chip or package, semiconductor companies need a comprehensive turnkey solution that encompasses key building blocks of design, redistribution, wafer bump, probe, assembly, test and supply chain management. As an OSAT provider, STATS ChipPAC provides value and impact to customers by offering a solutions-oriented approach rather than individual technologies or services. Our key approach is in integrating services such as design, assembly, test, and supply chain management customised to provide each customer with a customised solution from device inception to high volume manufacturing.

www.statschippac.com

STATSChipPAC™

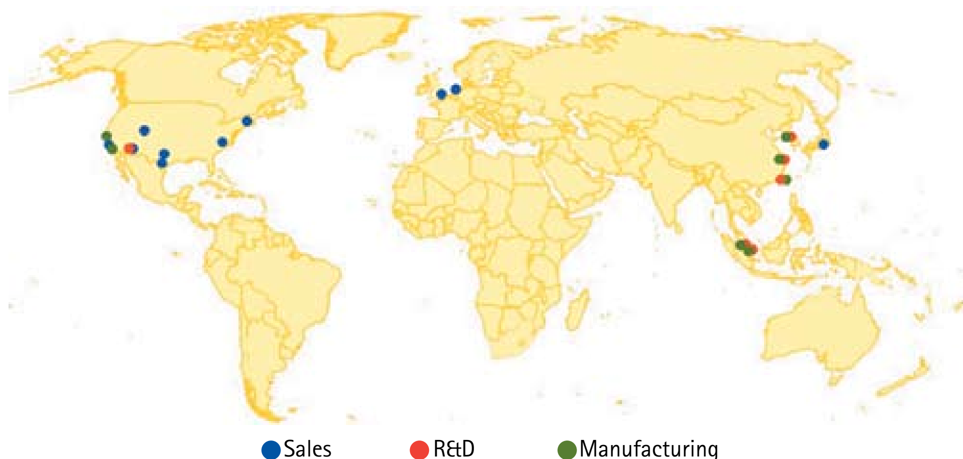
Global Presence in Strategic Markets

With advanced process technology capabilities and a global manufacturing presence spanning Singapore, China, South Korea, Malaysia, Taiwan, Thailand and the United States, STATS ChipPAC has a reputation for providing dependable, high quality test and packaging solutions.

The company's customer support offices are located in China, Singapore, Japan, Taiwan, Thailand, South Korea, Malaysia, the United Kingdom, the Netherlands, and the United States.

#1 Volume OSAT Company in China

- First to produce chip scale packaging in China
- High volume production in Plastic Ball Grid Array (PBGA) packages, three dimensional (3D) Stacking and system-in-package (SiP) solutions.
- High volume, low cost turnkey solutions (wafer probe, assembly, test and distribution)
- Significant lead over other semiconductor test and assembly service providers in China
- Serving the fast growing wireless market
- Awards from the Chinese government for exports



Shanghai, China: 422,000 ft^2 facility offers wafer sort, assembly and test services. Second 500,000 ft^2 facility expected to ramp up for production in various stages throughout 2007 to 2008.

Ichon, Korea: 587,000 ft^2 high-end facility specializes in advanced packaging such as flip chip, stacked die, chip scale packaging and BGA. Second 199,000 ft^2 facility expected to be completed in various stages throughout 2007 and 2008.

Kuala Lumpur, Malaysia: 488,000 ft^2 facility offers high volume assembly and test for a full range of mixed-signal and RF test.

Pathumthani, Thailand: 440,000 ft^2 facility offers high volume QFP packaging and test services.

Woodlands, Singapore: 10,200 ft^2 R&D facility specializes in next generation wafer integration technologies.

Yishun, Singapore: 594,000 ft^2 facility with state-of-the-art equipment, Class 10K clean room. Offers full turnkey services including wafer probe, assembly, final testing and drop shipment.

Hsin-Chu, Taiwan: 220,000 ft^2 facility specializes in wafer probe and final test. Second 7,000 ft^2 facility in Taiwan offers 300mm wafer electroplated solder bump services.

Milpitas and San Diego, California: 34,000 ft^2 and 20,000 ft^2 pre-production test houses offer complete semiconductor test services and new product integration support, final test and other high volume preparatory services.

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Oct 2007